



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-05-28
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacobello	Representative Title	IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	7BVT*106SBM1	A	SH1A	2015-05-28
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10,15,5,4,5	3	Through-hole	
Comment	Package: TO 220 I CLIP; MDF valid for T1035H-6I			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devi

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7BVT*10658M1						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
die (s)	Other inorganic materials	6.917	mg	supplier	die	Silicon (Si)	7440-21-3		6.099	mg	881741	3210	
die (s)				supplier	metallization	Aluminum (Al)	7429-90-5		0.056	mg	8096	29	
die (s)				supplier	metallization	Nickel (Ni)	7440-02-0		0.078	mg	11277	41	
die (s)				supplier	metallization	Gold (Au)	7440-57-5		0.017	mg	2458	9	
die (s)				supplier	passivation	Alumina	1344-28-1		0.049	mg	7084	26	
die (s)				supplier	passivation	Lead silicate Glass	65997-18-4	7c-I-Electrical and	0.444	mg	64190	234	
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.008	mg	1157	4	
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.166	mg	23999	87	
Leadframe	Copper & its alloys	1610.407	mg	supplier	alloy	Copper (Cu)	7440-50-8		1605.014	mg	996651	844744	
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.739	mg	459	389	
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		1.35	mg	838	711	
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		3.304	mg	2052	1739	
Soft solder	Solder	3.6	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.33	mg	925000	1753	
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.18	mg	50000	95	
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.09	mg	25000	47	
Soft solder -2	Solder	3.384	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.877	mg	850177	1514	
Soft solder -2				supplier	solder	Antimony (Sb)	7440-36-0		0.338	mg	99882	178	
Soft solder -2				supplier	solder	Tin (Sn)	7440-31-5		0.169	mg	49941	89	
Bonding wire	Other inorganic materials	31.625	mg	supplier	Slug + Trigger	Copper (Cu)	7440-50-8		31.625	mg	1000000	16645	
encapsulation	Other inorganic materials	148.553	mg	supplier	mold compound	Silica, vitreous	60676-86-0		120.328	mg	810000	63331	
encapsulation				supplier	mold compound	Phenol resin	8003-35-4		8.913	mg	59999	4691	
encapsulation				supplier	mold compound	Carbon black	1333-86-4		1.189	mg	8004	626	
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		15.152	mg	101997	7975	
encapsulation				supplier	mold compound	Metal hydroxide	Proprietary		2.971	mg	20000	1564	
connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	3323	
subelement	Ceramics / Glass	89.2	mg	supplier	Ceramic isolator	Nickel (Ni)	7440-02-0		1.07	mg	11996	563	
subelement				supplier	Ceramic isolator	Phosphorus (P)	12185-10-3		0.08	mg	897	42	
subelement				supplier	Ceramic isolator	Manganese (Mn)	7439-96-5		3.479	mg	39002	1831	
subelement				supplier	Ceramic isolator	Titanium (Ti)	7440-32-6		0.366	mg	4103	193	
subelement				supplier	Ceramic isolator	Molybdenum oxide	1313-27-5		4.46	mg	50000	2347	
subelement				supplier	Ceramic isolator	Alumina (Al2O3)	1344-28-1		79.745	mg	894002	41971	